

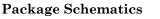
### Part Number: XZMGT54W-4

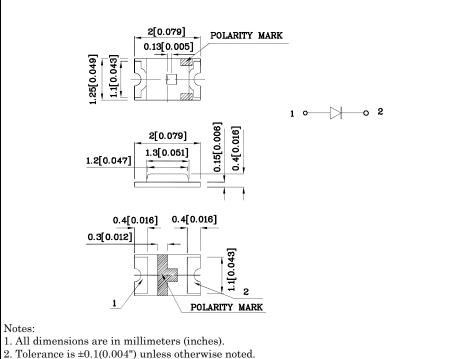
2.0x1.25mm SMD CHIP LED LAMP

#### **Features**

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Package : 2000pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant







3. Specifications are subject to change without notice.

Notes:

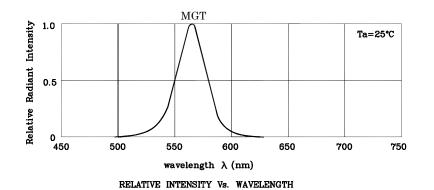
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MGT (GaP)	Unit	
Reverse Voltage	$V_{\mathrm{R}}$	5	V	
Forward Current	$\mathbf{I}_{\mathrm{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	PD	62.5	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	-40 ~ +85	-0	

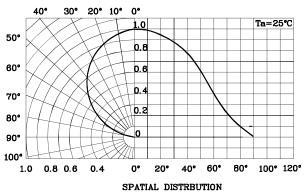
Operating Characteristics (T <sub>A</sub> =25°C)		MGT (GaP)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.2	V	
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.5	V	
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	10	uA	
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λP	565	nm	
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λD	568	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$ riangle\lambda$	30	nm	
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	$\mathrm{pF}$	

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMGT54W-4	Green	GaP	Water Clear	8	14	565	110°

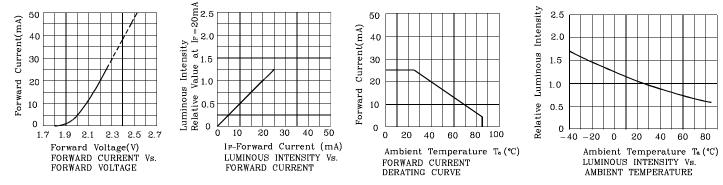
XDSA7254 V4 Layout: Maggie L.











# LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes: 1. Maximum soldering temperature should not exceed 260°C

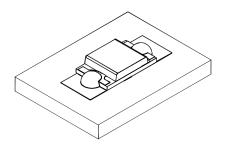
Maximum soldering temperature should not exceed 200°C
Recommended reflow temperature: 145°C-260°C

3. Do not put stress to the epoxy resin during

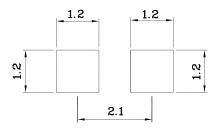
high temperatures conditions



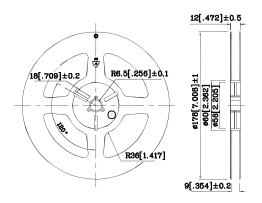
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



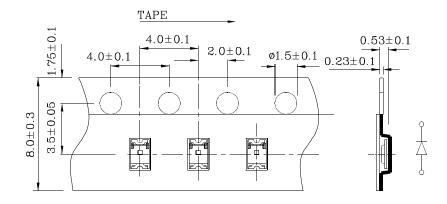
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



## Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V  $\,$ 

Note: Accuracy may depend on the sorting parameters.

Apr 11,2011



## PACKING & LABEL SPECIFICATIONS

